

L Number	Hits	Search Text	DB	Time stamp
1	367	257/778.ccls. and ((pad or land) with (gap or space or hole or spaces or spacing or slit or crack or cut or groove or slot or dam or open or opening))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:10
2	231	(257/778.ccls. and ((pad or land) with (gap or space or hole or spaces or spacing or slit or crack or cut or groove or slot or dam or open or opening))) and (@ad<20000512)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:57
3	9395	(chip or die or electronic or device or semiconductor) and (((substrate or board or carrier) and (ball or bump or solder)) with (recess or trench or groove or depression or via))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:36
4	6368	((chip or die or electronic or device or semiconductor) and (((substrate or board or carrier) and (ball or bump or solder)) with (recess or trench or groove or depression or via))) and (@ad<20000512)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:35
5	310	((chip or die or electronic or device or semiconductor) and (((substrate or board or carrier) and (ball or bump or solder)) with (recess or trench or groove or depression or via))) and (@ad<20000512)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:53
6	63	((((chip or die or electronic or device or semiconductor) and (((substrate or board or carrier) and (ball or bump or solder)) with (recess or trench or groove or depression or via))) and (@ad<20000512)) and (solder adj joint)) and ((vent or air or escape or gas) with (solder or joint or hole or groove or slit or slot or crack or opening or open or space or spacing or spaces or groove))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:57
7	48	((chip or die or electronic or device or semiconductor) and (((substrate or board or carrier) and (ball or bump or solder)) with (recess or trench or groove or depression or via))) and (@ad<20000512)) and ((solder adj joint) with (increase or enhance or strengthen or strength))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:56
8	30	((((chip or die or electronic or device or semiconductor) and (((substrate or board or carrier) and (ball or bump or solder)) with (recess or trench or groove or depression or via))) and (@ad<20000512)) and ((solder adj joint) with (increase or enhance or strengthen or strength))) not (((chip or die or electronic or device or semiconductor) and (((substrate or board or carrier) and (ball or bump or solder)) with (recess or trench or groove or depression or via))) and (@ad<20000512)) and (solder adj joint)) and ((vent or air or escape or gas) with (solder or joint or hole or groove or slit or slot or crack or opening or open or space or spacing or spaces or groove))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:54
9	289	((substrate or board or carrier) with (chip or die or device or semiconductor)) and ((solder adj joint) with (increase or enhance or strengthen or strength))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:57

10	231	((257/778.ccls. and ((pad or land) with (gap or space or hole or spaces or spacing or slit or crack or cut or groove or slot or dam or open or opening))) and (@ad<20000512)) and (@ad<20000512)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:57
11	32	((257/778.ccls. and ((pad or land) with (gap or space or hole or spaces or spacing or slit or crack or cut or groove or slot or dam or open or opening))) and (@ad<20000512)) and (@ad<20000512)) and ((air or escape or gas) with (vent or solder or joint or hole or groove or slit or slot or crack or opening or open or space or spacing or spaces or groove))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:58